

03/123 US

App No.: NEW

Docket No.: 4670-0128PUS1

Inventor: Takamitu MIKUNI et al.

Title: THERMALLY CONDUCTIVE PRESSURE-SENSITIVE ADHESIVE
COMPOSITION, THERMALLY CONDUCTIVE SHEET-FORM MOLDED
FOAM, AND PROCESS FOR PRODUCING THE SAME

NEW SHEET

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FIG. 1

